

IN THE SPECIFICATION:

Please amend the specification as follows:

Paragraph beginning on page 9, at prenumbered line 12, has been amended as follows:

Please refer to FIG. 7, which is the perspective view of the sixth embodiment according to present invention. As shown in the above figure, said heat sink-type cooling device for an integrated circuit 3 4 comprises a base 41 and plurality of fin 42 extended from an end surface of said base 41. Said plurality of fin 42 is divided into more than one heat zone 43,44 and said heat zones 43,44 have height drop between each two zones. Each of said plurality of heat zone 43,44 is framed by bending a mental plate. After said plurality of heat zone 43,44 is framed by bending said mental plate, a heat sink-type cooling device for an integrated circuit is made by putting it on said base 41.